

NOTES:

1. ALL DIMENSIONS ARE TO EXPOSED CORNER TO ANSI Y45-1982.
2. DATUM PLANE [C-C] IS LOCATED AT MOLD PARTING LINE AND PARTING LINE WITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT BOTTOM OF PARTING LINE.
3. DATUMS [D-D] AND [E-E] TO BE DETERMINED AT CENTERLINE BETWEEN LEADS WHERE LEADS EXIT PLASTIC BODY AT DATUM PLANE [E-E].
4. TO BE DETERMINED AT SEATING PLANE [E-E].
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
6. DIMENSIONS D2 AND E2 DO NOT INCLUDE MOLD PROTRUSION.
7. 1P IS THE TOTAL NUMBER OF TERMINALS.
8. THESE DIMENSIONS TO BE DETERMINED AT DATUM PLANE [E-E].
9. THESE DIMENSIONS ARE SMALLER THAN BOTTOM DIMENSIONS AND TOP OF PACKAGE WILL NOT OVERHANG BOTTOM OF PACKAGE.
10. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL THICKNESS. DAMBAR PROTRUSION CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.
11. CONTROLLING DIMENSION MILLIMETER.
12. MAXIMUM ALLOWABLE DIE THICKNESS TO BE ASSEMBLED IN THIS PACKAGE FAMILY IS 0.38 MILLIMETERS.
13. THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95.
14. AT IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
15. DIMENSION D2 AND E2 REPRESENT THE SIZE OF THE EXPOSED PAD. THE ACTUAL DIMENSIONS ARE SPECIFIED ON THE BONDING DIAGRAM, AND IS DEPENDENT ON THE DIE SIZE.
16. EXPOSED PAD SHALL BE COPLANAR WITH BOTTOM OF PACKAGE WITHIN 0.05.
17. CORNER CHAMFER OF EXPOSED DIE PAD SHALL BE WITHIN 0.30 MM.

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS

SYMBOL	ABA			D1	D2	E1	E2
	MIN.	NDM.	MAX.				
A	~	~	1.20	~	~	~	~
A1	0.05	~	0.15	~	~	~	~
A4	0.95	1.00	1.05	~	~	~	~
D	~	9.00 BSC.	~	~	~	~	~
D1	~	7.00 BSC.	~	~	~	~	~
D2	~	9.00 BSC.	~	~	~	~	~
E	~	9.00 BSC.	~	~	~	~	~
E1	~	7.00 BSC.	~	~	~	~	~
E2	~	9.00 BSC.	~	~	~	~	~
L	0.45	0.60	0.75	~	~	~	~
N	~	3E	~	~	~	~	~
P	~	0.60 BSC.	~	~	~	~	~
b	0.30	0.37	0.45	~	~	~	~
B1	0.30	0.35	0.40	~	~	~	~
CCC	~	~	0.10	~	~	~	~
DDD	~	~	0.20	~	~	~	~

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS

SYMBOL	ABC			D1	D2	E1	E2
	MIN.	NDM.	MAX.				
A	~	~	1.20	~	~	~	~
A1	0.05	~	0.15	~	~	~	~
A4	0.95	1.00	1.05	~	~	~	~
D	~	9.00 BSC.	~	~	~	~	~
D1	~	7.00 BSC.	~	~	~	~	~
D2	~	9.00 BSC.	~	~	~	~	~
E	~	9.00 BSC.	~	~	~	~	~
E1	~	7.00 BSC.	~	~	~	~	~
E2	~	9.00 BSC.	~	~	~	~	~
L	0.45	0.60	0.75	~	~	~	~
N	~	4E	~	~	~	~	~
P	~	0.5 BSC.	~	~	~	~	~
b	0.17	0.22	0.27	~	~	~	~
B1	0.17	0.20	0.23	~	~	~	~
CCC	~	~	0.08	~	~	~	~
DDD	~	~	0.08	~	~	~	~

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS

SYMBOL	ABD			D1	D2	E1	E2
	MIN.	NDM.	MAX.				
A	~	~	1.20	~	~	~	~
A1	0.05	~	0.15	~	~	~	~
A4	0.95	1.00	1.05	~	~	~	~
D	~	9.00 BSC.	~	~	~	~	~
D1	~	7.00 BSC.	~	~	~	~	~
D2	~	9.00 BSC.	~	~	~	~	~
E	~	9.00 BSC.	~	~	~	~	~
E1	~	7.00 BSC.	~	~	~	~	~
E2	~	9.00 BSC.	~	~	~	~	~
L	0.45	0.60	0.75	~	~	~	~
N	~	6E	~	~	~	~	~
P	~	0.4 BSC.	~	~	~	~	~
b	0.13	0.18	0.23	~	~	~	~
B1	0.13	0.16	0.19	~	~	~	~
CCC	~	~	0.08	~	~	~	~
DDD	~	~	0.07	~	~	~	~

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Chandler, Arizona, USA
Amkor Technology (Australia), Inc.
Sydney, Korea
Amkor Technology (Philippines), Inc.
Manila, Philippines



PACKAGE OUTLINE, MATRX, TOPP

7 x 7 mm BODY, 1.00/0.10 mm THICK, 1.00 mm THICK (OPTIONAL, 0.75)

32770

PRINTING IS SCALED TO FIT

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FORM N01 NOTREBUILDING